



Material Content Data Sheet



Sales Product Name		BSS131 H6327		Issued		1. August 2018		
MA#		MA001231780						
Package		PG-SOT23-3-5		Weight*		9.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		472	
	noble metal	gold	7440-57-5	0.017	0.18		1829	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20724	23025
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	non noble metal	copper	7440-50-8	3.000	32.08	32.22	320752	322104
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	783	783
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6077	
	plastics	epoxy resin	-	1.222	13.07		130652	
	inorganic material	silicondioxide	60676-86-0	4.405	47.08	60.76	470956	607685
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15997	15997
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30406	30406
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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